

What is claimed is:

1. A wafer-interposer assembly comprising:

a semiconductor wafer including a plurality of semiconductor die, each semiconductor die having a plurality of first electrical contact pads;

an interposer connected to the semiconductor wafer, the interposer including a plurality of second electrical contact pads respectively connected to at least some of the first electrical contact pads via conductive attachment elements such that the interposer and the semiconductor wafer are operable to be singulated into a plurality of chip assemblies; and

a communication interface integrally associated with the interposer and electrically connected to at least some of the second electrical contact pads.

2. The wafer-interposer assembly as recited in claim 1 wherein the communication interface further comprises an integral edge connector with pins.

3. The wafer-interposer assembly as recited in claim 1 wherein the communication interface further comprises an integral bayonet connector with pins.

4. The wafer-interposer assembly as recited in claim 1 wherein the communication interface further comprises a connector added to the wafer-interposer assembly.

5. The wafer-interposer assembly as recited in claim 1 wherein the communication interface further comprises soldered connections.

6. The wafer-interposer assembly as recited in claim 1 wherein the communication interface further comprises a ribbon connector.

7. The wafer-interposer assembly as recited in claim 1 wherein the communication interface further comprises an RF connector.

8. The wafer-interposer assembly as recited in claim 1 wherein the communication interface further comprises an optical connector.

9. The wafer-interposer assembly as recited in claim 1 wherein the communication interface further comprises a transmit/receive antenna.

10. The wafer-interposer assembly as recited in claim 1 wherein the communication interface further comprises a quick release device.

11. The wafer-interposer assembly as recited in claim 1 wherein the communication interface is operably coupled to a testing apparatus that tests at least some of the semiconductor die prior to the singulation of the interposer and the semiconductor wafer.

12. The wafer-interposer assembly as recited in claim 1 wherein the communication interface is operably coupled to a testing apparatus that burn-in tests at least some of the semiconductor die prior to the singulation of the interposer and the semiconductor wafer.

13. A wafer-interposer assembly comprising:

a semiconductor wafer including a plurality of semiconductor die, each semiconductor die having a plurality of first electrical contact pads;

an interposer disposed on the semiconductor wafer, the interposer including a plurality of second electrical contact pads respectively connected to the plurality of first electrical contact pads via conductive attachment elements such that the interposer and the semiconductor wafer are operable to be singulated into a plurality of chip assemblies; and

a communication interface integrally associated with the interposer and electrically connected to at least some of the second electrical contact pads.

14. The wafer-interposer assembly as recited in claim 13 wherein the interposer is disposed on the semiconductor wafer using a technique selected from the group consisting of ink jet deposition of conductive epoxy, soldering, polyimide deposition and stereolithographic techniques.

15. The wafer-interposer assembly as recited in claim 13 wherein the communication interface further comprises an integral edge connector with pins.

16. The wafer-interposer assembly as recited in claim 13 wherein the communication interface further comprises an integral bayonet connector with pins.

17. The wafer-interposer assembly as recited in claim 13 wherein the communication interface further comprises a connector added to the wafer-interposer assembly.

18. The wafer-interposer assembly as recited in claim 13 wherein the communication interface further comprises soldered connections.

19. The wafer-interposer assembly as recited in claim 13 wherein the communication interface further comprises a ribbon connector.

20. The wafer-interposer assembly as recited in claim 13 wherein the communication interface further comprises an RF connector.

21. The wafer-interposer assembly as recited in claim 13 wherein the communication interface further comprises an optical connector.

22. The wafer-interposer assembly as recited in claim 13 wherein the communication interface further comprises a transmit/receive antenna.

23. The wafer-interposer assembly as recited in claim 13 wherein the communication interface further comprises a quick release device.

24. The wafer-interposer assembly as recited in claim 13 wherein the communication interface is operably coupled to a testing apparatus that tests at least some of the semiconductor die prior to the singulation of the interposer and the semiconductor wafer.

25. The wafer-interposer assembly as recited in claim 13 wherein the communication interface is operably coupled to a testing apparatus that burn-in tests at least some of the semiconductor die prior to the singulation of the interposer and the semiconductor wafer.